

L Number	Hits	Search Text	DB	Time stamp
1	65	257/777.ccls. and (dielectric with (die or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/22 23:42
2	0	(mems with (circuit adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/22 23:43
3	0	(mems with ((circuit or redistribution) adj layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/22 23:45
4	1	("6228687").PN.	USPAT	2002/08/22 23:47
5	27	(csp or (chip near package)) and (mems or (micro near mechanical))	USPAT	2002/08/23 00:00
6	1	(csp or (chip near package)) and (external with (mems or (micro near mechanical)))	USPAT	2002/08/23 00:00

L Number	Hits	Search Text	DB	Time stamp
1	1	("6121688").PN.	USPAT	2002/08/23 05:00
2	20	(passive adj device) near capacitor	USPAT	2002/08/23 05:37
3	283	(wafer with (integration or scale)) and (heat adj (dissipation or sink or spreader or plug or slug))	USPAT	2002/08/23 05:39
4	283	((wafer with (integration or scale)) and (heat adj (dissipation or sink or spreader or plug or slug))) and (@ad<20011231)	USPAT	2002/08/23 05:40
5	214	((wafer with (integration or scale)) and (heat adj (dissipation or sink or spreader or plug or slug))) and (@ad<20011231)) and (chip or die)	USPAT	2002/08/23 05:40